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AMENDMENT / RESPONSE TRANSMITTAL

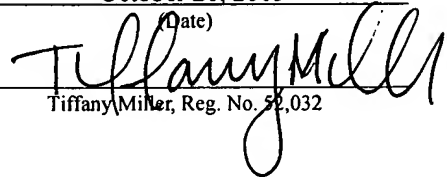
Applicant : Smythe, et al.
App. No : 10/782,997
Filed : February 19, 2004
For : SUB-MICRON SPACE LINER AND
DENSIFICATION PROCESS
Examiner : Christy L. Novacek
Art Unit : 2822

CERTIFICATE OF MAILING

I hereby certify that this correspondence and all marked attachments are being deposited with the United States Postal Service as first-class mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on

October 20, 2005

(Date)

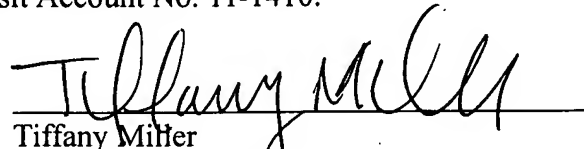

Tiffany Miller, Reg. No. 52,032

Mail Stop Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

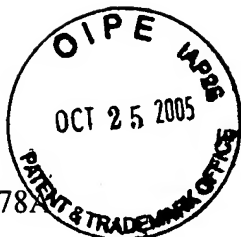
Sir:

Transmitted herewith for filing in the above-identified application are the following enclosures:

- (X) Response to Restriction Requirement in 2 pages.
- (X) Return prepaid postcard.
- (X) Please charge any additional fees, including any fees for additional extension of time, or credit overpayment to Deposit Account No. 11-1410.


Tiffany Miller
Registration No. 52,032
Attorney of Record
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IFW



MICRON.278A

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

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Tiffany Miller
Tiffany Miller, Reg. No. 52,032

RESPONSE TO RESTRICTION REQUIREMENT

Mail Stop Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Dear Sir:

In response to the Office Action dated September 23, 2005, Applicant submits the following remarks for consideration in connection with the above-identified patent application.